

MS1V-T1K Product Documentation

Product Documentation

MS1V-T1K

Quartz Crystal Unit 32.768 kHz

April 2022 1/12 Rev. 1.1

2. Product Description

The MS1V-T1K is a low frequency surface mount technology Quartz Crystal Unit that incorporates a tuning fork Quartz Crystal Resonator. The Quartz Crystal Resonator operates under vacuum condition in a hermetically sealed square-bodied metal can package.

Suitable oscillator-circuitries can operate the MS1V-T1K Quartz Crystal Units in fundamental mode consuming very low power. For technical assistance for optimizing oscillator-circuitries please contact Micro Crystal under sales@microcrystal.com

2.1. Application Examples

IoT Metering Wearables Health Care Consumer Electronics

2.2. Ordering Information

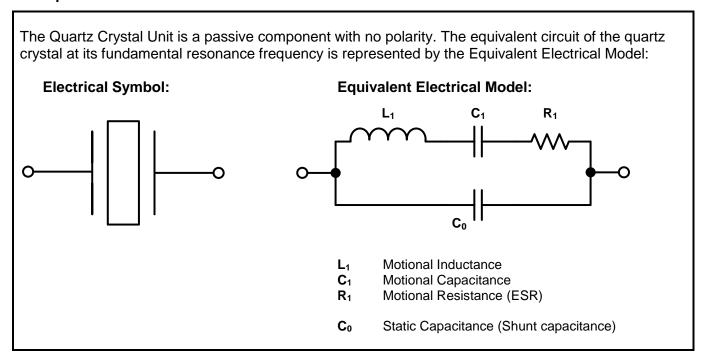
Example: MS1V-T1K 32.768 kHz CL: 12.5 pF -20/+20ppm TA QC

Code	Operating temperature range
TA	-40 to +85°C

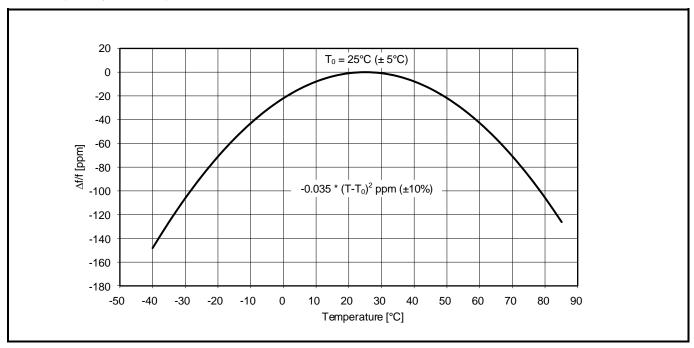
Code	Qualification
QC	Commercial Grade

3. Electrical Characteristics

3.1. Equivalent Electrical Model

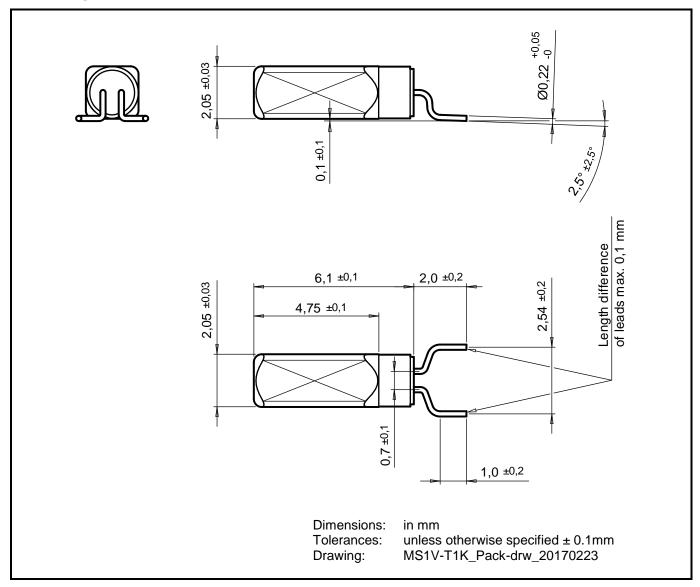


3.2. Frequency vs Temperature Characteristics

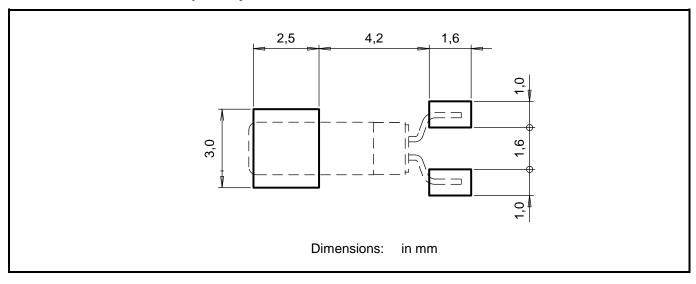


4. Mechanical Properties

4.1. Package Dimension



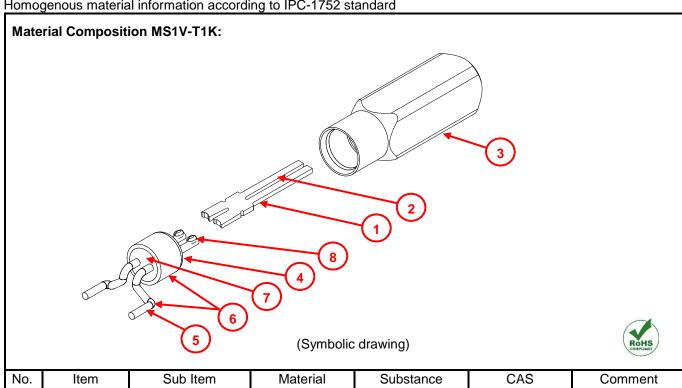
4.2. Recommended Solderpad Layout



5. Material Composition Declaration & Environmental Information

5.1. Homogenous Material Composition Declaration

Homogenous material information according to IPC-1752 standard



No.	Item Component	Sub Item Material	Material Weight		Substance Element	CAS Number	Comment
	Name	Name	(mg)	(%)			
1	Resonator	Quartz Crystal	0.65	100%	SiO ₂	14808-60-7	
2	Electrodes	Cr+Au	0.01	6% 94%	Cr Au	7440-47-3 7440-57-5	
3	Сар	Brass	94.1	99.3%	Cu58Zn39Pb3	12597-71-6	Pb RoHS exempt in copper alloys up to 4% (exemption (6(c))
		Ni-plating		0.6%	Ni, 1 micron	Ni: 7440-02-0	
		Au-plating		0.1%	Au, 0.05 micron	Au: 7440-57-5	
4	Holder ring	Alloy 42	5.5	100%	Fe57Ni42Mn1	Fe: 7439-89-6 Ni: 7440-02-0 Mn: 7439-96-5	
5	Leads	Kovar	1.5	100%	Fe53Ni29Co18	Fe: 7439-89-6 Ni: 7440-02-0 Co: 7440-48-4	
6	Lead plating	Cu-plating Solder-plating	1.5	13% 71%	Cu, 2 micron Pb93Sn7, 9 micron	7440-50-8 Pb: 7439-92-1 Sn: 7440-31-5	Pb RoHS exempt in high temperature solder with more than 85% lead (exemption 7(a))
		Ag-plating Au-flashed		15% 1%	Ag, 2 micron Au, 0.1 micron	Ag: 7440-22-4 Au: 7440-57-5	
7	Seal	Glass	6.0	100%		65997-17-3	
8	Resonator attach	Silver filled Epoxy	0.075	30% 70%	Epoxy resin Ag	129915-35-1 7440-22-4	
		Unit weight	109.3				

5.2. Material Analysis & Test Results

Homogenous material information according to IPC-1752 standard

No.	Item	Sub Item	RoHS					Halogens			Phthalates					
	Component Name	Material Name		рЭ	Hg	Cr(VI)	PBB	PBDE	F	IO	Br	1	BBP	DBP	DEHP	DINP
1	Resonator	Quartz Crystal	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
2	Electrodes	Cr+Au	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
3	Сар	Brass		RoHS 5 ppm	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
4	Holder ring	Alloy 42	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
5	Leads	Kovar	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
6	Lead plating	Cu+SnPb+Ag+Au	RoHS 92.34%	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
7	Seal	Glass	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
8	Resonator attach	Silver filled Epoxy	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
	MDL	Method Detection Limit		2 p	pm		5 p	pm		50 p	opm		(0.003%	6	0.01%

nd (not detected) = below "Method Detection Limit" (MDL) RoHS = RoHS compliant, substances accepted by RoHS Directive

Test methods:

RoHS Test method with reference to:

IEC 62321-5:2013 MDL: Pb, Cd 2 ppm IEC 62321-4:2013 MDL: 2 ppm Hg Cr(VI) IEC 62321:2008 MDL: 2 ppm PBB / PBDE IEC 62321:2008 MDL: 5 ppm Test method with reference to BS EN 14582:2007 MDL: 50 ppm **Halogens**

Phthalates Test method with reference to EN 14372:2004 MDL: 0.003% (DINP 0.01%)

5.3. Recycling Material Information

Recycling material information according to IPC-1752 standard.

Element weight is accumulated and referenced to the unit weight of 109.3 mg.

Item Material	No.	Item Component	Material Weight		Substance Element	CAS Number	Comment
Name		Component Name	(mg)	(%)	Element	Number	
Quartz Crystal	1	Resonator	0.65	0.59	SiO ₂	14808-60-7	
Chromium	2	Electrodes	0.0006	0.0005	Cr	7440-47-3	
Brass	3	Cap	93.44	85.46	Cu58Zn39Pb3	12597-71-6	
Gold	2 3 6	Electrodes Cap Lead plating	0.12	0.11	Au	7440-57-5	
Nickel	3	Сар	0.56	0.52	Ni	Ni: 7440-02-0	
Alloy 42	4	Holder ring	5.50	5.03	Fe57Ni42Mn1	Fe: 7439-89-6 Ni: 7440-02-0 Mn: 7439-96-5	
Kovar	5	Leads	1.50	1.37	Fe53Ni29Co18	Fe: 7439-89-6 Ni: 7440-02-0 Co: 7440-48-4	
Copper	6	Lead plating	0.20	0.18	Cu	7440-50-8	
Solder SnPb	6	Lead plating	1.06	0.97	Pb93Sn7	Pb: 7439-92-1 Sn: 7440-31-5	
Silver	6 8	Lead plating Resonator attach	0.28	0.25	Ag	7440-22-4	
Glass	7	Seal	6.00	5.49		65997-17-3	
Ероху	8	Resonator attach	0.02	0.02	Epoxy resin	129915-35-1	
	Unit v	weight (total)	109.3	100			

5.4. Environmental Properties & Absolute Maximum Ratings

Package	Description	
Metal Package	Hermetic metal-package, with formed leads.	

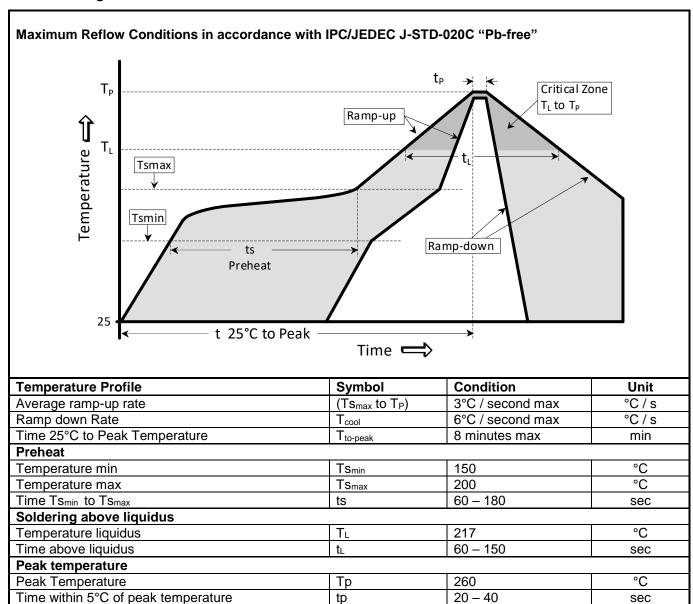
Parameter	Directive	Conditions	Value
Product weight (total)			109.3 mg
Storage temperature		Store as bare product	-55 to +85°C
Moisture sensitivity level (MSL)	IPC/JEDEC J-STD-020D		MSL 1
FIT / MTBF			available on request

Finish for Holder ring and Leads:



6. Application Information

6.1. Soldering Information



6.2. Handling Instructions for Quartz Crystal Units

The built-in tuning-fork crystal consists of pure Silicon Dioxide in crystalline form. The cavity inside the package is evacuated and hermetically sealed in order for the crystal blank to function undisturbed from air molecules, humidity and other influences.

Shock and vibration:

Keep the crystal / module from being exposed to **excessive mechanical shock and vibration**. Micro Crystal guarantees that the crystal / module will bear a mechanical shock of 5000 g / 0.3 ms.

The following special situations may generate either shock or vibration:

Multiple PCB panels - Usually at the end of the pick & place process the single PCBs are cut out with a router. These machines sometimes generate vibrations on the PCB that have a fundamental or harmonic frequency close to 32.768 kHz. This might cause breakage of crystal blanks due to resonance. Router speed should be adjusted to avoid resonant vibration.

Ultrasonic cleaning - Avoid cleaning processes using ultrasonic energy. These processes can damage the crystals due to the mechanical resonance frequencies of the crystal blank.

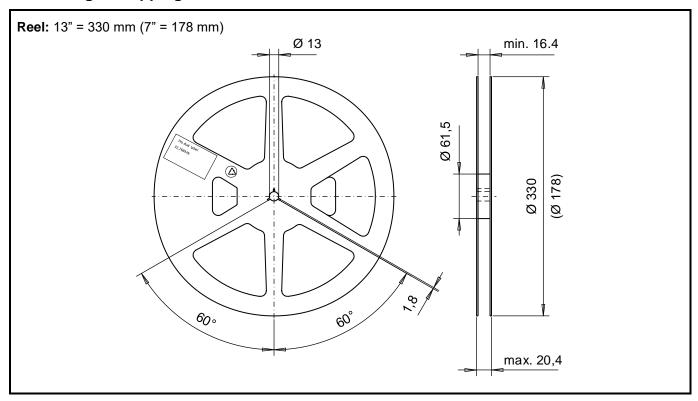
Overheating, rework high temperature exposure:

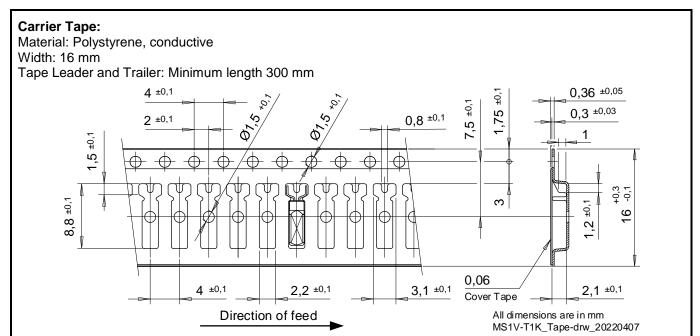
Avoid overheating the package. The package is sealed with a solder consisting of 93% Lead and 7% Tin. The melting temperature of this alloy is at 280°C. Heating the package up to >280°C will cause melting of the metal seal which then, due to the vacuum, is sucked into the cavity forming an air duct. This happens when using hot-air-gun set at temperatures >280°C.

Use the following method for rework:

Use a hot-air-gun set at 270°C.

7. Packing & Shipping Information





Cover Tape:

Tape: Polypropylene, 3M™ Universal Cover Tape (UCT) Adhesive Type: Pressure sensitive, Synthetic Polymer

Thickness: 0.06 mm

Peel Method:

Medial section removal, both lateral stripes remain on carrier

8. Compliance Information

Micro Crystal confirms that the standard product Quartz Crystal Unit MS1V-T1K is compliant with "EU RoHS Directive" and "EU REACh Directives".

Please find the actual Certificate of Conformance for Environmental Regulations on our website: CoC Environment MS-Series.pdf

9. Document Revision History

Date	Revision #	Revision Details
February 2017	1.0	First release
April 2022	1.1	Corrected Ordering Information, 2.2. Added "Dimensions: in mm", 4.1. and 4.2. Removed "SiO ₂ " in item 8 (Glass), 5.1. and 5.3. Described test methods in more detail, 5.2. Corrected maximum storage temperature from +125°C to +85°C, 5.4. Corrected text to "hot-air-gun set at temperatures >280°C.", 6.2. Replaced Tape drawing with new version, 7. Updated CoC Hyperlink, 8. Added new disclaimer

The information contained in this document is believed to be accurate and reliable. However, Micro Crystal assumes no responsibility for any consequences resulting from the use of such information nor for any infringement of patents or other rights of third parties, which may result from its use. In accordance with our policy of continuous development and improvement, Micro Crystal reserves the right to modify specifications mentioned in this publication without prior notice and as deemed necessary.

Any use of Products for the manufacture of arms is prohibited. Customer shall impose that same obligation upon all third-party purchasers.

Without the express written approval of Micro Crystal, Products are not authorized for use as components in safety and life supporting systems as well as in any implantable medical devices. The unauthorized use of Products in such systems / applications / equipment is solely at the risk of the customer and such customer agrees to defend and hold Micro Crystal harmless from and against any and all claims, suits, damages, cost, and expenses resulting from any unauthorized use of Products.

No licenses to patents or other intellectual property rights of Micro Crystal are granted in connection with the sale of Micro Crystal products, neither expressly nor implicitly. In respect of the intended use of Micro Crystal products by customer, customer is solely responsible for observing existing patents and other intellectual property rights of third parties and for obtaining, as the case may be, the necessary licenses.



Micro Crystal AG Muehlestrasse 14 CH-2540 Grenchen Switzerland Phone +41 32 655 82 82 sales@microcrystal.com www.microcrystal.com